SDLS147 - SEPTEMBER 1972 - REVISED MARCH 1988

- Three-State Version of SN54/74LS153, SN54/74S153
- Schottky-Diode-Clamped Transistors
- Permits Multiplexing from N Lines to 1 Line
- Performs Parallel-to Serial Conversion
- Fully Compatible with Most TTL Circuits
- Low Power Dissipation

'LS253 . . . 35 mW Typical 'S253 . . . 225 mW Typical

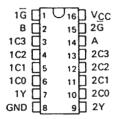
description

Each of these Schottky-clamped data selectors/multiplexers contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to the AND-OR gates. Separate output control inputs are provided for each of the two four-line sections.

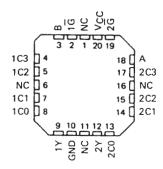
The three-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at a high-impedance state) the low-impedance of the single enabled output will drive the bus line to a high or low logic level.

SN54LS253, SN54S253 . . . J OR W PACKAGE SN74LS253, SN74S253 . . . D OR N PACKAGE

(TOP VIEW)



SN54LS253, SN54S253...FK PACKAGE (TOP VIEW)



NC-No internal connection

FUNCTION TABLE

1	ECT UTS		DATA	INPUTS	OUTPUT CONTROL	ОUТРUТ	
В	Α	CO	C1	C2	C3	Ğ	Υ
X	X	X	X	X	X	Н	Z
Ł	L	L	X	X	Х	L	L
L	L	Н	X	×	X	L	н
L	Н	X	L	X	X	L	L
L	Н	X	Н	X	X	L	н
Н	L	X	X	L	X	L	L
н	L	X	X	Н	X	L	Н
Н	Н	X	X	X	L	L	L
Н	Н	Х	×	X	Н	L	Н

Address inputs A and B are common to both sections.

H = high fevel, L = low level, X = irrelevant, Z = high impedance (off)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

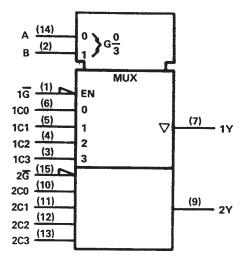
Supply voltage, VCC (see Note 1)			 7 V
Input voltage: 'LS253			 7 V
′S253			 5.5 V
Off-state output voltage			
Operating free-air temperature range	: SN54LS253, SN54S253	; 	 - 55°C to 125°C
	SN74LS253, SN74S253		
Storage temperature range			 -65° C to 150° C

NOTE 1: Voltage values are with respect to network ground terminal.

TEXAS INSTRUMENTS

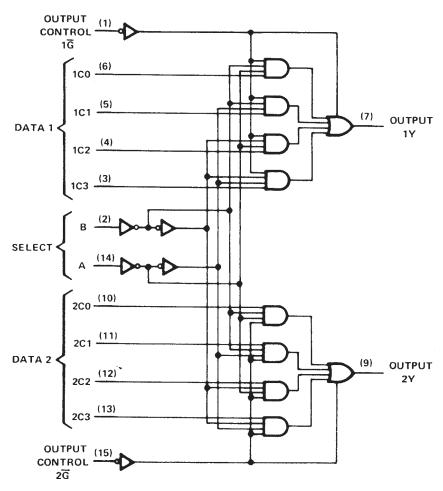
SDLS147 - SEPTEMBER 1972 - REVISED MARCH 1988

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

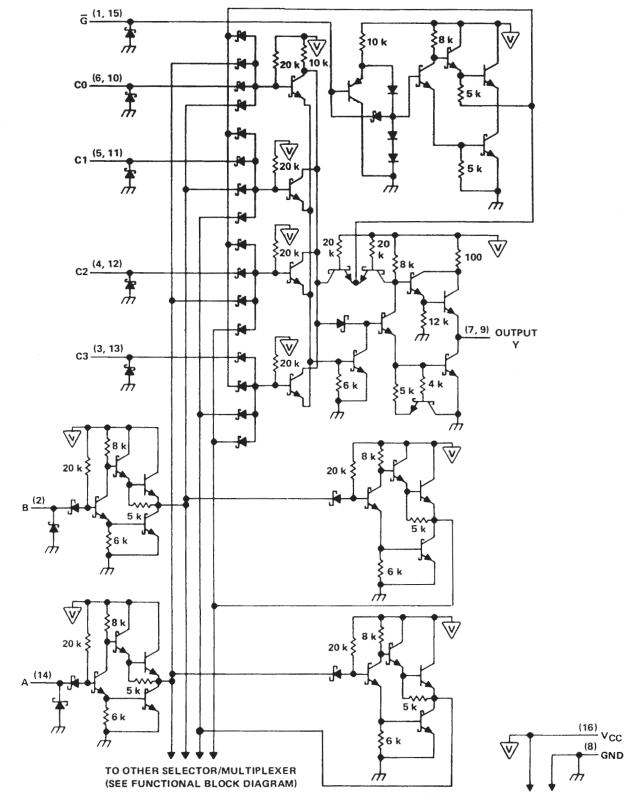
logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



schematic (each selector/multiplexer, and the common select section)



Pin numbers shown are for D, J, N, and W packages.



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recommended operating conditions

		S	SN54LS253			SN74LS253			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
Іон	High-level output current			- 1			2.6	mA	
IOL	Low-level output current			4			8	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS [†]						S	N74LS2	53	LINUT
FANAMETEN		1521 CONDITI	ONS		MIN	TYP \$	MAX	MIN	TYP‡	MAX	UNIT
VIK	VCC = MIN,	$I_1 = -18 \text{ mA}$					- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{IH} = 2 V,	VIL = MAX,	1 _{OH} = MAX	2.4	3.4		2.4	3.1		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	1/ - 14AV	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	ACC - MIIA	VIH - 2 V,	VIL = MAX	IOL = 8 mA					0.25	0.5	
loz	VCC = MAX,	V _{IH} = 2 V		V _O = 2.7 V			20			20	
102	VCC - WAX,	VIH - Z V		V _O = 0.4 V			- 20			20	μΑ
11	V _{CC} = MAX,	V ₁ = 7 V					0.1			0.1	mΑ
liH.	V _{CC} = MAX,	V _I = 2.7 V					20			20	μΑ
1	V _{CC} = MAX,	V ₁ = 0.4 V		Ğ			- 0.2			- 0.2	
115	VCC - MAA,	V - 0.4 V		All other			- 0.4			- 0.4	, mA
Ios§	V _{CC} = MAX				- 30		- 130	- 30		- 130	mA
loo	V _{CC} = MAX,	See Note 2		Condition A		7	12		7	12	
¹cc	VCC - WAA,	See Note 2		Condition B		8.5	14		8.5	14	mA

[†] For conditions shown as MIN or MAX, use the appropriate value spcified under recommended operating conditions.

NOTE 2: I_{CC} is measured with the outputs open under the following conditions:

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
^t PLH	Data	Y			17	25	
tPHL	Data	'			13	20	ns
^t PLH	Select		$C_L = 15 pF$, $R_L = 2 k\Omega$,		30	45	
tPHL.	Select	'	See Note 3		21	32	ns
^t PZH	Output	_			15	28	
^t PZL	Control	'			15	23	ns
^t PHZ	Output		$C_L = 5 \text{ pF}, \qquad R_L = 2 \text{ k}\Omega,$		27	41	
^t PLZ	Control		See Note 3		18	3 27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and duration for the short-circuit should exceed one second.

A. All inputs grounded.

B. Output control at 4.5 V, all inputs grounded.

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recommended operating conditions

			SN54S253			SN74S253			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8			0.8	V	
ЮН	High-level output current			-2			- 6.5	mA	
IOL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			MIN	түр‡	MAX	UNIT			
VIK	VCC = MIN,			-1.2	V				
Voн	VCC = MIN,	V _{1H} = 2 V,	V _{1L} = 0.8 V,	IOH = MAX	Series 54S	2,5	3.4		V
*OH	VCC - WITH,	VIH - 2 V,	VIL - 0.8 V,	IOH = MAX	Series 74S	2.7	3.4		1 °
VOL	VCC = MIN,	VIH = 2 V,	VIL = 0.8 V,	IOL = 20 mA				0.5	V
loz	Vcc = MAX,	VIH = 2 V			V _O = 2.4 V			50	
.02	VCC - WAX,	VIH - 2 V		V _O = 0.5 V			- 50	μA	
l ₁	V _{CC} = MAX,	V1 = 5.5 V						1	mA
ΙΗ	V _{CC} = MAX,	V _I = 2.7 V						50	μΑ
111	V	V 0.5.V.			G = 0.8 V			- 2	
-11.	VCC = MAX,	$V_1 = 0.5 V$			G = 2 V			- 0.25	mA
los§	V _{CC} = MAX				1	- 40		- 100	mA
¹cc	V _{CC} = MAX,	See Note 2		Condition A				70	
	TOG = WAX,	See Note 2	Condition B		65	85	mA		

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second.

NOTE 2: I_{CC} is measured with the outputs open under the following conditions:

- A. All inputs grounded.
- B. Output control at 4.5 V, all inputs grounded.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TYP	MAX	UNIT	
^t PLH	Data	~			6	9	
^t PHL	Data	'			6	9	ns
^t PLH	Select		$R_{L} = 280 \Omega$	C _L = 15 pF	11.5	18	
^t PHL	Journal	'	See Note 3	OL 10 Pi	12	18	ns
^t PZH	Output				11	16.5	
^t PZL	Control	,			12	18	ns
^t PHZ	Output		R _L = 280 Ω,	C _L = 5 pF	6.5	9.5	
^t PLZ	Control	See Note 3		10	15	ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.





28-Nov-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
76017012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
7601701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
7601701EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
7601701FA	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701FA SNJ54LS253W	
7601701FA	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701FA SNJ54LS253W	
JM38510/30908B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30908B2A	
JM38510/30908B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30908B2A	
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30908B2A	
M38510/30908B2A	NRND	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 30908B2A	
M38510/30908BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/	Samples





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Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5) 30908BFA	
SN54LS253J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS253J	_
31134L32333	ACTIVE	CDIP	J	10	ı,	IBD	A42	N/A for Pkg Type	-55 (0 125	31134L32333	Samples
SN54LS253J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS253J	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS253J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	0 to 70		
SN74LS253N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Sample
SN74LS253N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Sample
SN74LS253N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS253N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S253N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74S253N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Sample
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Sample
SNJ54LS253J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Sample
SNJ54LS253J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Sample
SNJ54LS253W	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701FA SNJ54LS253W	
SNJ54LS253W	NRND	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7601701FA SNJ54LS253W	

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

PACKAGE OPTION ADDENDUM



28-Nov-2015

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS253, SN74LS253:

Catalog: SN74LS253

Military: SN54LS253

NOTE: Qualified Version Definitions:



TEXAS INSTRUMENTS

28-Nov-2015

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





		Dimension designed to accommodate the component width
		Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
1	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS253DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

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*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74LS253DR	SOIC	D	16	2500	333.2	345.9	28.6

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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